

## SSC80211GN4

#### P-Channel Enhancement Mode MOSFET

#### > Features

V <sub>DS</sub>	V <sub>GS</sub>	R <sub>DS(ON)</sub> Typ.	ID
-20V	+12V	6.2mΩ@-10V	-55A
	<u> </u>	8.5mΩ@-4V5	-00A

#### > Description

This SSC80211GN4 uses advanced trench technology to provide excellent RDSON and low gate charge. The complementary MOSFETS may be used to form a level shifted high side switch, and for a host of other applications.

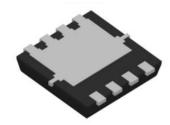
100% UIS + ΔVDS + Rg Tested!

- > Applications
- Load Switch
- PWM Application
- Power Management

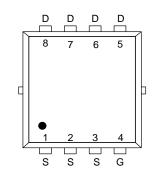
#### > Ordering Information

Device	Package	Shipping	
SSC80211GN4	PDFN3.3X3.3-8L	5000/Reel	

#### Pin configuration



PDFN3.3X3.3-8L (Bottom View)



#### Pin Configuration (Top View)



<u>Marking</u>







Symbol	Parameter	Ratings	Unit	
V <sub>DSS</sub>	Drain-to-Source Voltage		-20	V
V <sub>GSS</sub>	Gate-to-Source Volta	Gate-to-Source Voltage		V
		Tc=25℃	-55	٨
lo	Continuous Drain Current <sup>d</sup>	Tc=100℃	-30	A
	Continuous Drain Current <sup>a</sup>	T <sub>A</sub> =25℃	-17	٨
DSM		T <sub>A</sub> =70℃	-12	A
Ідм	Pulsed Drain Current <sup>b</sup>		-220	А
D		Tc=25℃	31.2	W
PD	Power Dissipation <sup>c</sup>	Tc=100℃	12.5	
D	Power Dissipation <sup>a</sup>	T <sub>A</sub> =25℃	3.13	W
Pdsm		T <sub>A</sub> =70℃	2	
Eas	Avalanche Energy <sup>b</sup> L=0.5mH Single Pulse		90	mJ
TJ	Operation junction temperature		-55~150	°0
T <sub>STG</sub>	Storage temperature range		-55~150	Ĉ

#### > Absolute Maximum Ratings ( $T_A=25^{\circ}C$ unless otherwise noted)

#### > Thermal Resistance Ratings ( $T_A=25^{\circ}C$ unless otherwise noted)

Symbol	Parameter	Ratings	Unit
R <sub>0JA</sub>	Junction-to-Ambient Thermal Resistance <sup>a</sup>	40	°C/W
R <sub>θJC</sub>	Junction-to-Case Thermal Resistance	4	C/W

Note:

- a. The value of R<sub>θJA</sub> is measured with the device mounted on 1 in<sup>2</sup> FR-4 board with 2oz.copper, in a still air environment with T<sub>A</sub>=25 °C.The value in any given application depends on the user is specific board design. The power dissipation is based on the t≤10s thermal resistance rating.
- b. Repetitive rating, pulse width limited by junction temperature.
- c. The power dissipation P<sub>D</sub> is based on T<sub>J(MAX)</sub>=150°C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heat sinking is used.
- d. The maximum current rating is package limited.





# $\succ$ Electrical Characteristics (T<sub>A</sub>=25 °C unless otherwise noted)

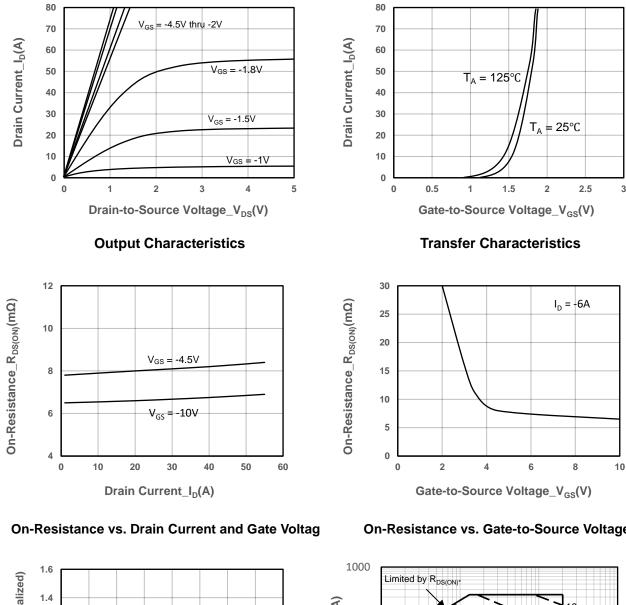
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Drain-Source Breakdown Voltage	V <sub>(BR)</sub> dss	$V_{GS} = 0V, I_D = -250 \mu A$	-20			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = -250 uA$	-0.4	-0.8	-1.2	V
Drain Course On Desistance	RDS(on)	$V_{GS} = -10V, I_D = -10A$		6.2	8.3	mΩ
Drain-Source On-Resistance		$V_{GS} = -4.5V, I_D = -6A$		8.5	10.5	
Zero Gate Voltage Drain Current	Idss	$V_{DS}$ = -20V, $V_{GS}$ = 0V			1	μA
Gate-Source Leak Current	Igss	$V_{GS} = \pm 20V$ , $V_{DS} = 0V$			±100	nA
Forward Voltage	V <sub>SD</sub>	$V_{GS} = 0V$ , $I_S = -1A$			-1.2	V
Gate Resistance	Rg	$V_{DS} = 0V, f = 1MHz$		12		Ω
Input Capacitance	Ciss			4300		
Output Capacitance	Coss	$V_{DS} = -10V, V_{GS} = 0V,$ f = 1MHz		480		pF
Reverse Transfer Capacitance	C <sub>RSS</sub>			450		
Total Gate Charge	Q <sub>G</sub>			55		
Gate to Source Charge	Q <sub>GS</sub>	$V_{GS} = -4.5V, V_{DS} = -10V,$ $I_{D} = -10A$		8		nC
Gate to Drain Charge	Q <sub>GD</sub>	$I_D = -10A$		15		
Turn-on Delay Time	T <sub>D(ON)</sub>			11		
Rise Time	Tr	$V_{GS} = -10V, V_{DD} = -10V,$		108		
Turn-off Delay Time	T <sub>D(OFF)</sub>	$I_D = -10A, R_G = 2.7\Omega$		155		ns
Fall Time	T <sub>f</sub>			158		

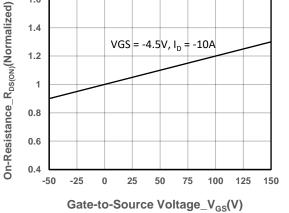
SSC-V1.0



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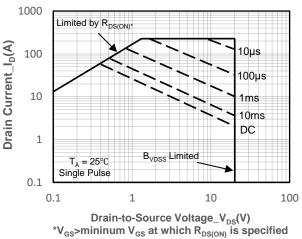
#### Typical Performance Characteristics ( $T_A=25^{\circ}C$ unless otherwise noted) $\triangleright$





**On-Resistance vs. Junction Temperature** 

**On-Resistance vs. Gate-to-Source Voltage** 



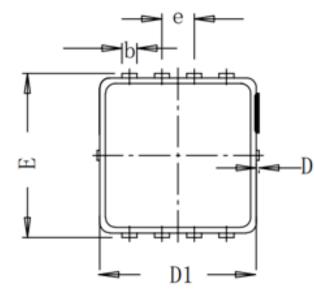
#### Safe Operating Area vs. Junction-to-Ambient

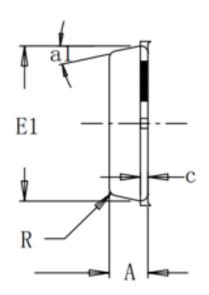
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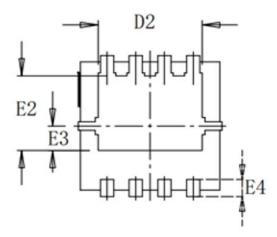


# SSC80211GN4

### Package Information







Symbol	Dimensions In Millimeters			
Symbol	Min.	Nom.	Max.	
Α	0.75	0.78	0.81	
b	0.297	0.3	0.35	
С	-	0.152	-	
D	0	0.05	0.1	
D1	3.12	3.15	3.18	
D2	-	2.35	-	
Е	3.2	3.3	3.4	
E1	3.09	3.12	3.15	
E2	-	1.75	-	
E3	-	0.575	-	
E4	-	0.4	-	
R	-	0.15	-	
e	0.65BSC			
a1°	-	12°	-	





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